# Negative Voltage Margining and Scaling Circuit With Voltage Output Smart DAC



Smart DAC Katlynne Jones

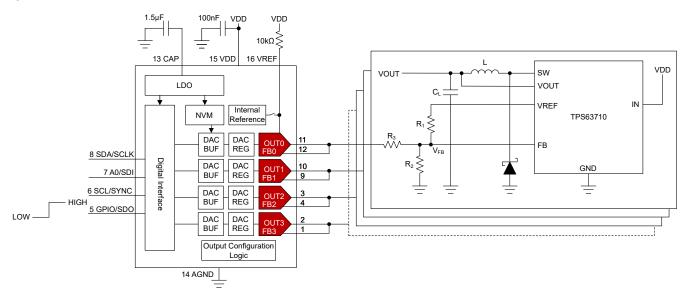
**Design Objective** 

Key Input Parameter	Key Output Signal	Recommended Device	
SPI or I <sup>2</sup> C communication to	0-V to 1.2-V programmable current sink, –3.45 V	DAC63204W, DAC53204W, DAC63004W, DAC53004W,	
control DAC voltage output	±26% DC/DC output	DAC63204, DAC53204, DAC43204, TPS63710	

Objective: Margin a DC/DC output to ±26% the nominal value.

### **Design Description**

This circuit uses a four-channel buffered voltage output DAC to margin an inverting step-down DC/DC converter. A voltage margining circuit is used to trim, scale, or test the output of a power converter. Adjustable power supplies, such as low dropout regulators (LDOs), DC/DC converters, or switch-mode power supplies (SMPS) provide a feedback (FB) pin that is used, along with a resistive voltage divider, to control the desired output. A precision smart DAC, such as the DAC63204W or DAC53204W (DACx3204W), provides linear control of the power supply output by using a series resistor to inject current into the voltage divider. The DACx3204 have a general-purpose input (GPI) pin that allows the DAC output to be toggled between a high and low voltage output. This allows the DC/DC to be toggled within ±26% of the nominal output value. All register settings are saved using the integrated non-volatile memory (NVM), enabling the device to be used without runtime software, even after a power cycle or reset. This circuit can be used in applications such as LIDAR, virtual reality headsets, and OLED TVs.



#### **Design Notes**

- The DACx3204W 12-Bit and 10-Bit, Quad Voltage and Current Output Smart DACs With Auto-Detected I2C, SPI, or PMBus® Interface in DSBGA Package data sheet recommends using a 100-nF decoupling capacitor for the VDD pin and a 1.5-μF or greater bypass capacitor for the CAP pin. The CAP pin is connected to the internal LDO. Place these capacitors close to the device pins.
- 2. Connect a 100-nF capacitor from the VREF pin to GND if the external reference is used. Ramp up the external reference after VDD. Connect a pullup resistor from the VREF pin to VDD if the external reference is not used. This example uses the internal reference and the VREF pin is pulled up to VDD with a  $10-k\Omega$  resistor.
- 3. The output voltage (V<sub>OUT</sub>) of the TPS63710 when the DAC63204W is not connected or the current through the series resistor, R<sub>3</sub>, is 0 A set by resistors R<sub>1</sub> and R<sub>2</sub>. The TPS63710 uses an internal –700-mV reference voltage (V<sub>FB</sub>) at the FB pin to determine V<sub>OUT</sub>. The current through R<sub>3</sub> is 0 A when the DAC63204W output voltage (V<sub>DAC</sub>) equals V<sub>FB</sub>. The DAC63204W cannot output a negative voltage, so this design assumes that the DAC63204W output is always positive, and the TPS63710 is at the nominal output voltage when the DAC63204W is at midscale.
- 4. Choose  $R_3$  so that  $V_{DAC} > -0.3$  V when the DAC63204W is set to power-down mode. When the DAC63204W is configured in 10 k $\Omega$  to GND power-down mode, the 10-k $\Omega$  resistance creates a resistor divider with  $R_3$ .  $R_3$  is chosen to be 200 k $\Omega$  in this example, making  $V_{DAC}$  equal to -0.038 V when in 10 k $\Omega$  to GND power down. Do not use Hi-z power-down mode when a negative voltage is connected to  $V_{DAC}$ .
- 5. Choose the current through  $R_2$  ( $I_{R2}$ ) so that the bias current into the FB pin of the TPS63710 is negligible.  $R_2$  is calculated using:

$$R_2 = \frac{V_{FB}}{I_{R2}}$$

 $I_{R2}$  is chosen to be 5.2  $\mu$ A. The TPS63701 has an internal gain factor of 1/0.9 which makes the effective  $V_{FB}$  –778 mV.  $R_2$  is calculated to be:

$$R_2 = \frac{|-778 \text{ mV}|}{5.2 \text{ uA}} = 150 \text{ k}\Omega$$

6. The nominal TPS63710  $V_{OUT}$  is chosen to be -3.45 V when  $V_{DAC}$  is at midscale, or 0.91 V. The current sourced from the DAC63204W output is calculated by:

$$I_{DAC} = \frac{V_{DAC} - V_{FB}}{R_3}$$

$$I_{DAC} = \frac{910 \text{ mV} + 778 \text{ mV}}{200 \text{ k}\Omega} = 8.44 \text{ } \mu\text{A}$$

R<sub>1</sub> can be calculated to achieve the desired nominal V<sub>OUT</sub> using:

$$R_1 = \frac{v_{FB} - v_{OUT}}{I_{R2} - I_{DAC}}$$

$$R_1 = \frac{-0.778 \, V + 3.45 \, V}{5.2 \, \mu A + 8.44 \, \mu A} = 196 \, k\Omega$$

7. The DAC63204W sinks or sources additional current through R<sub>1</sub> by adjusting V<sub>DAC</sub> to achieve the desired margin. V<sub>DAC</sub> is calculated by:

$$V_{DAC} = \left(I_{R2} - \frac{V_{OUT} - V_{FB}}{R_1}\right) \times R_3 + V_{FB}$$

 $V_{DAC,MAX}$  and  $V_{DAC,MIN}$  are configured to margin  $V_{OUT}$  by 26%.  $V_{OUT}$  low is -4.34 V and  $V_{OUT}$  high is -2.55 V

$$V_{DAC,\,MAX} = \left(-5.2~\mu\text{A} - \frac{-4.34~\text{V} + 0.778~\text{V}}{196~\text{k}\Omega}\right) \times 200~\text{k}\Omega - 0.778~\text{V} = 1.82~\text{V}$$

$$V_{DAC, MIN} = \left(-5.2 \,\mu A - \frac{-2.55 \,V + 0.778 \,V}{196 \,k\Omega}\right) \times 200 \,k\Omega - 0.778 \,V = 0 \,V$$

The DAC codes for V<sub>DAC,MAX</sub> and V<sub>DAC,MIN</sub> are stored in the DAC-X-MARGIN-HIGH and DAC-X-MARGIN-LOW registers. V<sub>DAC,NOM</sub> is stored in the DAC-X-DATA register. The codes programmed to these registers, in decimal, is calculated using:

$$DAC\_CODE = \frac{V_{DAC} \times 2^{12}}{V_{REF}}$$

This design uses the internal 1.21-V reference with a gain of ×1.5 giving a full-scale voltage of 1.82 V. The equations become:

DAC\_MARGIN\_HIGH = 
$$\frac{1.82 \text{ V} \times 2^{12}}{1.82 \text{ V}} = 4096 \text{d}$$

$$DAC_DATA = \frac{0.91 \text{ V} \times 2^{12}}{1.82 \text{ V}} = 2048d$$

$$DAC\_MARGIN\_LOW = \frac{0 \text{ V} \times 2^{12}}{1.82 \text{ V}} = 0d$$

The maximum output code for a 12-bit device is 4095 so the V<sub>DAC,MAX</sub> becomes 1.819 V.

- 9. The TPS63710 requires that  $V_{IN} \ge |V_{OUT}| / 0.7$ . The max  $V_{OUT}$  for this application is -4.34 V, so the minimum  $V_{IN}$  is 6.2 V. 10 V is used in this design.
- 10. Using a 1.21-V reference with a  $\times$ 1.5 gain and the 12-bit DAC63204W, the LSB size, or step size between each code, is about 443  $\mu$ V. Using the lowest reference voltage possible decreases the LSB size and thus maximizes the resolution of V<sub>DAC,MAX</sub> and V<sub>DAC,MIN</sub>.
- 11. The DAC63204W has a programmable slew-rate feature. The programmable slew is configured with the CODE-STEP-X and SLEW-RATE-X fields in the DAC-X-FUNC-CONFIG register. The programmable slew is only available when toggling between two values stored in the DAC-X-MARGIN-HIGH and DAC-X-MARGIN-LOW registers.

CODE-STEP-X defines the number of LSB steps used to transition from the starting code to the final output code. SLEW-RATE-X defines the time-period for each code step. The slew time is calculated by:

$$t_{SLEW} = SLEW\_RATE \times CEILING \Big( \frac{MARGIN\_HIGH\_CODE - MARGIN\_LOW\_CODE}{CODE\_STEP} + 1 \Big)$$

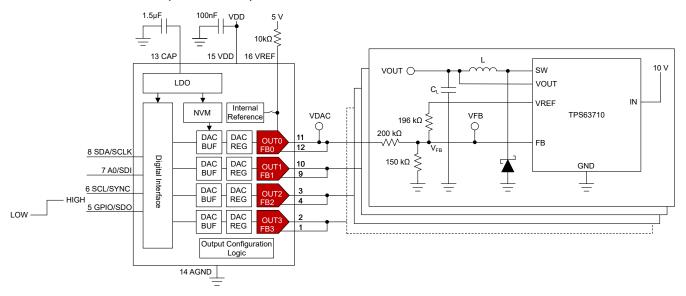
This application uses a margin high code of 4095, margin low code of 0, SLEW-RATE of 1282 μs/LSB and a CODE-STEP of 1 LSB to achieve a 5.25-s slew time:

$$t_{SLEW} = 1282 \left(\mu \text{s/LSB}\right) \times \text{CEILING} \left(\frac{4095 - 0}{1 \text{ LSB}} + 1\right) = 5.25 \text{ s}$$

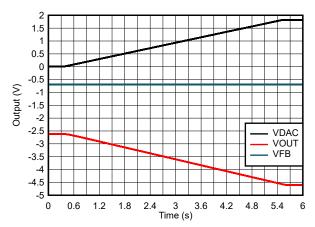
- 12. The GPIO pin can be configured as a digital input to switch the DAC63204W output between the margin high and margin low outputs with a programmable slew. The GPI-EN bit in the GPIO-CONFIG register enables the GPIO pin as an input. The GPI-CH-SEL field selects which channels are controlled by the GPI. The GPI-CONFIG field selects the GPI function. Write 0b1010 to the GPI-CONFIG field to configure the GPIO pin to trigger margin-high or margin-low functions.
  - A high on GPI sets the DAC output to V<sub>DAC,MAX</sub> and the TPS63710 V<sub>OUT</sub> to low, or –4.34 V. A low on GPI sets the DAC output to V<sub>DAC,MIN</sub> and the TPS63710 V<sub>OUT</sub> to high, or –2.55 V.
- 13. The DAC63204W can be programmed with the initial register settings described in the Register Settings section using I<sup>2</sup>C or SPI. Save the initial register settings in the NVM by writing a 1 to the NVM-PROG field of the COMMON-TRIGGER register. After programming the NVM, the device loads all registers with the values stored in the NVM after a reset or a power cycle.

## **Design Results**

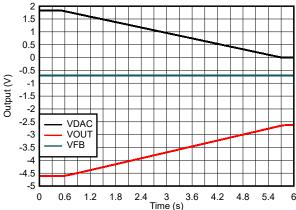
This schematic is used for the following design results of the DAC63204W. The  $V_{DAC}$ ,  $V_{OUT}$ , and  $V_{FB}$  signals are measured on an oscilloscope at the test points marked on the schematic.



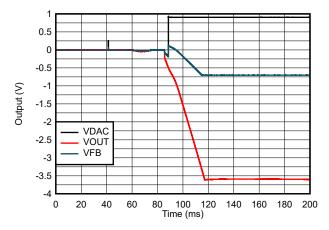
This plot shows the low-to-high transition of the DAC63204W output with the 5.25-s slew configured using the settings discussed in the Design Notes. The  $V_{DAC}$  output voltage slews from 0 V to 1.82 V which causes the TPS63710  $V_{OUT}$  voltage to slew from -2.55 V to -4.34 V.



This plot shows the low-to-high transition of the DAC63204W output with the 5.25-s slew. The  $V_{DAC}$  output voltage slews from 1.82 V to 0 V which causes the TPS63710  $V_{OUT}$  voltage to slew from -4.34 V to -2.55 V.



This plot shows the start-up behavior of the circuit. The 10-V TPS63710 supply and 5-V DAC63204W supply are switched on at the same time. The  $V_{DAC}$  output starts up to the nominal voltage of 910 mV. The TPS63710  $V_{OUT}$  ramps to the nominal output of -3.45 V as the  $V_{FB}$  reference voltage starts up.



## **Register Settings**

The following table shows an example register map for this application. The values given here are for the design choices made in the Design Notes section.

**Register Settings for DAC63204W** 

Register Address	ter Address Register Name Setting Description				
0x1F	COMMON-CONFIG	0x1249	[15] 0b0: Write 0b0 to set the window-comparator output to a non- latching output		
			[14] 0b0: Device not locked		
			[13] 0b0: Fault-dump read enable at address 0x00		
			[12] 0b1: Enables the internal reference		
			[11:10] 0b00: Powers up VOUT3		
			[9] 0b1: Powers down IOUT3		
			[8:7] 0b00: Powers up VOUT2		
			[6] 0b1: Powers down IOUT2		
			[5:4] 0b00: Powers up VOUT1		
			[3] 0b1: Powers down IOUT1		
			[2:1] 0b00: Powers up VOUT0		
			[0] 0b1: Powers down IOUT0		
0x24	GPIO-CONFIG	0x01F5	[15] 0b0: Glitch filter disabled for GP input		
			[14] 0b0: Don't care		
			[13] 0b0: Disable output mode for GPIO pin		
			[12:9] 0b0000: Selects the STATUS function setting mapped to GPIO as output		
			[8:5] 0b1111: Enables GPI function on all channels		
			[4:1] 0b1010: GP input configured to trigger margin high or low		
			[0] 0b1: Enables input mode for GPIO pin		



Register Settings for DAC63204W (continued)

Register Address	Register Name	Setting	Description
0x20	COMMON-TRIGGER	0x0002	[15:12] 0b0000: Write 0b0101 to unlock the device
			[11:8] 0b0000: Write 0b1010 to trigger a POR reset
			[7] 0b0: LDAC is not triggered
			[6] 0b0: DAC clear is not triggered
			[5] 0b0: Don't care
			[4] 0b0: Fault-dump is not triggered
			[3] 0b0: PROTECT function not triggered
			[2] 0b0: Fault-dump read not triggered
			[1] 0b1: Write 0b1 to store applicable register settings to the NVM
			[0] 0b0: NVM reload not triggered. Write 0b1 to reload applicable registers with existing NVM settings
0x03, 0x09, 0x0F,	DAC-X-VOUT-CMP- CONFIG	0x0800	[15:13] 0b000: Don't care
0x15			[12:10] 0b010: Selects internal reference with ×1.5 gain
			[9:5] 0x00: Don't care
			[4] 0b0: Set OUTx pins as push-pull in comparator mode
			[3] 0b0: Comparator output consumed internally
			[2] 0b0: FBx input has high-impedance in comparator mode
			[1] 0b0: Comparator output not inverted
			[0] 0b0: Disable comparator mode
0x06, 0x0C, 0x12,	DAC-X-FUNC-CONFIG	0x000D	[15] 0b0: DAC-X clear mode set to zero-scale
0x18			[14] 0b0: DAC-X output updates immediately after a write command
			[13] 0b0: Do not update DAC-X with broadcast command
			[12:11] 0b00: Phase set to 0°
			[10:8] 0b000: Selects sine wave mode
			[7] 0b0: Enable linear slew
			[6:4] 0b000: Selects 8 LSB CODE-STEP
			[3:0] 0xD: Selects 8 µs/step SLEW-RATE
0x01, 0x07, 0x0D,	DAC-X-MARGIN-HIGH	0xFFF0	[15:4] 0xFFF: 12-bit margin high code
0x13			[3:0] 0x0: Don't care
0x02, 0x08, 0x0E,	DAC-X-MARGIN-LOW	0x0000	[15:4] 0x000: 12-bit margin low code
0x14			[3:0] 0x0: Don't care
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#### **Pseudocode Example**

The following shows a pseudocode sequence to program the initial register values to the NVM of the DAC63204W. The values given here are for the design choices made in the Design Notes section.

#### Pseudocode Example for DAC63204W

//SYNTAX: WRITE <REGISTER NAME (Hex code)>, <MSB DATA>, <LSB DATA> //Set gain setting to 1.5x internal reference (1.8 V) (repeat for all channels) WRITE DAC-0-VOUT-CMP-CONFIG(0x3), 0x08, 0x00 //Power-up voltage output on all channels and enable the internal reference 4: WRITE COMMON-CONFIG(0x1F), 0x12, 0x49//Configure GPI for Margin-High, Low trigger for all channels WRITE GPIO-CONFIG(0x24), 0x01, 0xF5
//Set slew rate and code step (repeat for all channels) //CODE\_STEP: 1 LSB, SLEW\_RATE: 1282 µs/step 9. 10: WRITE DAC-0-FUNC-CONFIG(0x06), 0x00, 0x0D11: //write nominal DAC code (repeat for all channels) 12: //For a 1.8-V output range, the 12-bit hex code for 0.9 V is 0x800. With 16-bit left alignment, 13: this becomes 0x8000 14: WRITE DAC-0-DATA(0x19), 0x80, 0x00
15: //write DAC margin high code (repeat for all channels) 16: //For a 1.8-V output range, the 12-bit hex code for 1.8 V is 0xFFF. With 16-bit left alignment, 17: this becomes 0xFFF0 18: WRITE DAC-0-MARGIN-HIGH(0x01), 0xFF, 0xF0
19: //write DAC margin low code (repeat for all channels)
20: //The 12-bit hex code for 0 v is 0x000. With 16-bit left alignment, this becomes 0x0000 21: WRITE DAC-0-MARGIN-LOW(0x02), 0x00, 0x00 21: //Save settings to NVM 22: WRITE COMMON-TRIGGER(0x20), 0x00, 0x02



**Design Featured Devices** 

Device	Key Features	Link
DAC63204W	4-channel, 12-bit, VOUT and IOUT smart DAC with I <sup>2</sup> C, SPI, and Hi-Z out during power off in DSBGA package	DAC63204W
DAC53204W	4-channel, 10-bit, VOUT and IOUT smart DAC with I <sup>2</sup> C, SPI, and Hi-Z out during power off in DSBGA package	DAC53204W
DAC63004W	4-channel, 12-bit, VOUT and IOUT smart DAC with I <sup>2</sup> C, SPI, and Hi-Z out during power off in DSBGA package	DAC63004W
DAC53004W	4-channel, 10-bit, VOUT and IOUT smart DAC with I <sup>2</sup> C, SPI, and Hi-Z out during power off in DSBGA package	DAC53004W
TPS63710	Low Noise, 1 A Synchronous Inverting Buck Converter in 3x3 WSON Package	TPS63710

Find other possible devices using the Parametric search tool.

## **Design References**

See Analog Engineer's Circuit Cookbooks for TI's comprehensive circuit library.

#### **Additional Resources**

- Texas Instruments, DAC63004WCSP-Evaluation Module
- Texas Instruments, DAC63004WCSP-EVM User's Guide
- Texas Instruments, Precision Labs DACs
- Texas Instruments, TPS63710EVM-811

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